

REMARKS

The specification has been amended to correct typographical errors. In addition, claims 1 and 5 have been amended. Claims 1-20 remain pending in the captioned case. Further examination and reconsideration of the presently claimed application are respectfully requested.

Allowable Subject Matter

Claims 8-20 were allowed in their present form. Applicants appreciate the Examiner's indication of allowable subject matter. However, for reasons set forth below, Applicants believe that claims 1-7 are also allowable over the cited references.

Section 102 Rejection

Claims 1-7 were rejected under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 5,856,937 to Chu et al. (hereinafter "Chu"). The standard for "anticipation" is one of fairly strict identity. A claim is anticipated only if each and every element as set forth in the claim is found, either expressly or inherently described, in a single prior art of reference. *Verdegaal Bros. v. Union Oil Co. of California*, 2 USPQ2d 1051, 1053 (Fed. Cir. 1987); MPEP 2131. Furthermore, anticipation requires the presence in a single prior art reference disclosure of each and every element of the claimed invention, as arranged in the claim. *W.I. Gore & Assocs. V. Garlock*, 721 F.2d 1540, 220 USPQ 303 (Fed. Cir. 1983). Using these standards, Applicants submit the cited art fails to disclose each and every element of the currently pending claims, some distinctive features of which are set forth in more detail below.

Chu does not teach or suggest a unibody via extending along an axis perpendicular to the first and second outside surfaces of a printed circuit board, and extending entirely through the printed circuit board. Present independent claim 1 recites a unibody via. The unibody via extends along an axis perpendicular to the first and second outside surfaces of a printed circuit board. The via also extends entirely through the printed circuit board, and is coupled between a primary conductor on the first outside surface and a secondary conductor on the second outside surface. Present Fig. 5 illustrates via 40 which extends perpendicular to the first and second outside surfaces 24a and 24b (Specification -- Fig. 5). Moreover, via 40 is coupled between a primary conductor on surface 24a and a secondary conductor on

surface 24b. Therefore, via 40 does not consist of several vias, some of which extend perpendicular and some of which extend parallel to surfaces 24a and 24b, as in the cited art.

Contrary to present claim 1, Chu indicates that via holes can be drilled through a substrate interconnect layer or layers (Chu -- col. 2, lines 46-48). Moreover, Chu indicates the vias are used to connect a power supply pin of an SRAM chip and capacitors on the back surface to a power supply pin of an SRAM chip on the front surface, or vice versa (Chu -- col. 5, lines 31-34). A closer reading of Chu makes clear that the power supply and ground supply are maintained a dielectrically spaced distance apart within the multi-layer substrate, labeled as reference numeral 76 and 78 of Fig. 6 (Chu -- Fig. 6). Thus, the power layer 76 and the ground layer 78 carry power and ground to the power-supply pins and ground-supply pins of SRAM chips 20 and 40 through vias 64 and 68, as well as vias 66 and 62 (Chu -- Fig. 6; col. 5, lines 31-46).

Clearly illustrated in Chu, vias 64-68 do not extend entirely through substrate 10. Moreover, if the combination of, for example, via 64, layer 76, and via 62 is somehow hypothetically considered to be a single via, nowhere in Chu is it suggested that via 64, layer 76, and via 62 which are interconnected together comprise a unibody via, nor is there any suggestion that the combination of these three routes extend along an axis perpendicular to the opposed outer surfaces. Accordingly, Applicants respectfully traverse this rejection as to claims 1-7.

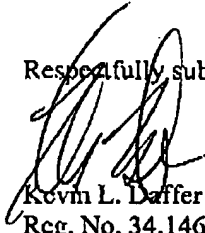
For at least the reasons set forth above, Applicants assert that independent claim 1 and claims dependent therefrom, are not anticipated by the cited art. Therefore, Applicants respectfully request removal of this rejection.

CONCLUSION

The present amendment and response is believed to be a complete response to the issues raised in the Office Action mailed February 9, 2005. In view of the remarks traversing the rejections, Applicant asserts that pending claims 1-20 are in condition for allowance. If the Examiner has any questions, comments or suggestions, the undersigned attorney earnestly requests a telephone conference.

No fees are required for filing this amendment; however, the Commissioner is authorized to charge any additional fees that may be required, or credit any overpayment, to LSI Logic Corp. Deposit Account No. 12-2252/03-1236.

Respectfully submitted,


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Date: April 25, 2005